FORM PTO-1595 RECORD (Rev. 6-93) OMB No. 0651-0011 (exp. 4/94)	PATION FORM COVER SHEET PATENTS ONLY	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office	
To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.			
Name of conveying party(ies):	2. Name and address of red	ceiving party(ies)	
Infineon Technologies North America Corp	name: Infineon Technologie:	s AG	
	Internal Address:		
Additional name(s) of conveying party(ies) attached		Stront Address:	
Nature of conveyance:	Street Address:		
_X_Assignment Merger	StMartin-Str. 53 81669 München GERMANY		
Security Agreement Change			
Other			
Execution Date: May 20, 2004	Additional name(s) & address(es	Additional name(s) & address(es) attached? Yes X No	
Execution Butto. May 25: 255:			
Application number(s) or patent number(s):			
If this document is being filed together with a new application, the execution date of the application is:			
A. Patent Application No.(s)	B. Patent No.(s)		
10/379,346	1		
	Additional numbers attached?	Yes _X_No	
Name and address of party to whom correspondence concerning document should be mailed:	ondence 6. Total number of applicati	ons and patents involved: 1	
Name: <u>Heather Rowland</u>	7. Total Fee (37 CFR 3.41)	\$ <u>40.00</u>	
Internal Address:			
Infineon Technologies North America Corp.	<u> </u>	Enclosed _X_ Authorized to be charged to deposit account	
I <u>ENA CPC IC</u>	X Authorized to be ch		
Street Address: 3000 CentreGreen Way			
	8. Deposit Account No.		
City: <u>Cary</u> State: <u>NC</u> ZIP: <u>275</u> 1	502912		
DO NOT USE THIS SPACE			
9. Statement and signature To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Marie-Claire Maple, Esq. Reg. No: 37,588 Name of Person Signing Total number of pages including cover sheet, attachments, and document: 3			

IDNR: 5427 Infineon US - Assignment IFNA Recordation Sheet 15/07/03

Atty. Docket No.: 2002P11670US

ASSIGNMENT

For good and valuable consideration, We, Infineon Technologies North America Corp., hereinafter referred to as Assignor, hereby sells, assigns and transfers to Infineon Technologies AG, a corporation, organized and existing under the laws of Germany, having its principal place of business at St. Martin Str. 53, 81669 Munich, Germany,

hereinafter referred to as Assignee, its successors, assigns and legal representatives, the entire right, title and interest, in and for the United States and all foreign countries, in and to any and all inventions which are disclosed in the application for United States Letters patent, and which was recorded on reel 013833, frame 0905 on March 4, 2003;

Serial No.: 10/379,346 Filed: March 4, 2003

and entitled: Reduction of the Shear Stress in Copper Via's In Organic Interlayer Dielectric Material

in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said inventions; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said inventions;

Assignor agrees that Assignee may apply for and receive Letters Patent for said inventions in its own name;

Assignor agrees that, at the request of the Assignee and, without charge to but at the expense of said Assignee, Assignor will carry out in good faith the intent and purpose of this Assignment; execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said inventions; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to Assignee, facts known to the undersigned relating to said inventions and the history thereof; and generally do everything possible which

> PATENT REEL: 014656 FRAME: 0077

-2-

Assignee shall consider desirable for aiding in securing and mainlining proper patent protection for said inventions and for vesting title to said inventions, and all applications for patents and all patents on inventions in said Assignee;

Covenant with Assignee that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Infineon Technologies North America Corp.

Its Assistant Secretary Duly

Dated: May 20, 2004

RECORDED: 05/20/2004